

NCEP12T12D

NCE N-Channel Super Trench Power MOSFET

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Description

The NCEP12T12D uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{\text{DS(ON)}}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

General Features

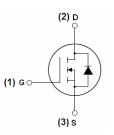
- $V_{DS} = 120V, I_D = 129A$ $R_{DS(ON)} < 5.3 \text{m}\Omega @ V_{GS} = 10V$
- Excellent gate charge x R_{DS(on)} product
- Very low on-resistance R_{DS(on)}
- 175 °C operating temperature
- Pb-free lead plating
- 100% UIS tested

Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

100% UIS TESTED!

100% ΔVds TESTED!



Schematic diagram



Marking and pin assignment



TO-263-2L top view

Package Marking and Ordering Information

	<u> </u>				
Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCEP12T12D	NCEP12T12D	TO-263-2L	-	-	=

Absolute Maximum Ratings (T_c=25°Cunless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	120	V
Gate-Source Voltage	V _{GS}	±20	V
Drain Current-Continuous	I _D	129	А
Drain Current-Continuous(T _C =100 °C)	I _D (100℃)	92	А
Pulsed Drain Current	I _{DM}	480	А
Maximum Power Dissipation	P _D	185	W
Derating factor		1.3	W/°C
Single pulse avalanche energy (Note 5)	E _{AS}	1000	mJ
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 175	$^{\circ}$



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NCEP12T12D

Thermal Characteristic

Thermal Resistance, Junction-to-Case (Note 2)	Rejc	0.8	°C/W	1
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Electrical Characteristics (T_C=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			•			
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	120		-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =120V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)			•			
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	2.5	3.3	4.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =60A	-	4.8	5.3	mΩ
Forward Transconductance	g _{FS}	V _{DS} =10V,I _D =60A	60	-	-	S
Dynamic Characteristics (Note4)	<u> </u>					
Input Capacitance	C _{lss}	\/ -50\/\/ -0\/	-	5600	-	PF
Output Capacitance	C _{oss}	V_{DS} =50V, V_{GS} =0V, F=1.0MHz	-	641	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.UIVIHZ	-	28	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		-	16	-	nS
Turn-on Rise Time	t _r	V_{DD} =60 V , I_D =60 A	-	67	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10 V , R_{G} =4.7 Ω	-	45	-	nS
Turn-Off Fall Time	t _f		-	14	-	nS
Total Gate Charge	Qg	V -00VI -00A	-	84.7		nC
Gate-Source Charge	Q_{gs}	$V_{DS}=60V, I_{D}=60A,$	-	30.6		nC
Gate-Drain Charge	Q_{gd}	V _{GS} =10V	-	18.3		nC
Drain-Source Diode Characteristics			•			•
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =129A	-		1.2	V
Diode Forward Current (Note 2)	Is		-	-	129	Α
Reverse Recovery Time	t _{rr}	$T_J = 25^{\circ}C$, $I_F = I_S$	-	60		nS
Reverse Recovery Charge	Qrr	$di/dt = 100A/\mu s^{(Note3)}$	-	140		nC

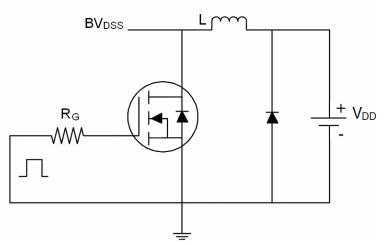
Notes:

- ${\it 1. Repetitive Rating: Pulse width limited by maximum junction temperature.}\\$
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition : Tj=25 $^{\circ}\text{C}$,V $_{\text{DD}}$ =50V,V $_{\text{G}}$ =10V,L=0.5mH,Rg=25 Ω

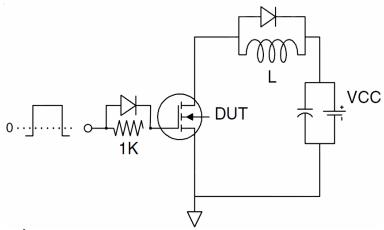


Test Circuit

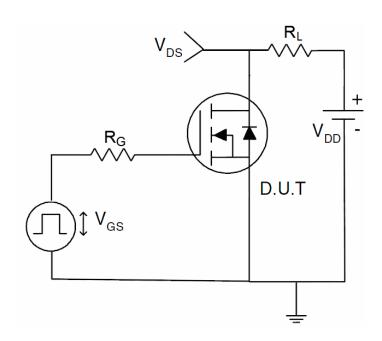
1) E_{AS} test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit





Typical Electrical and Thermal Characteristics

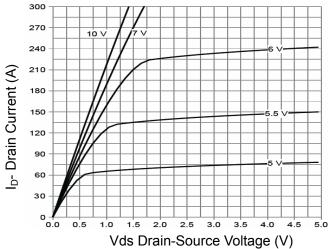


Figure 1 Output Characteristics

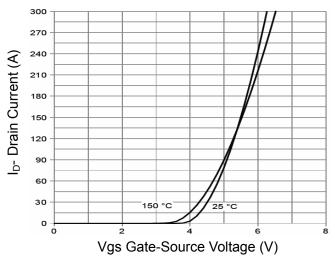


Figure 2 Transfer Characteristics

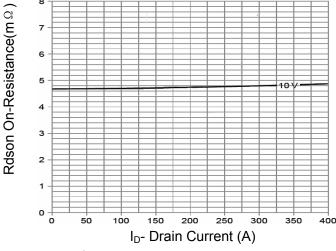


Figure 3 Rdson- Drain Current

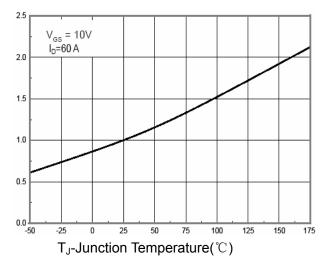


Figure 4 Rdson-JunctionTemperature

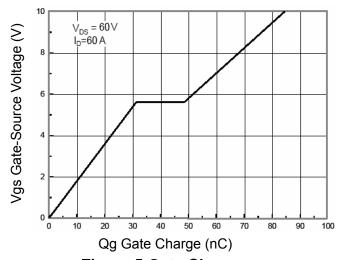


Figure 5 Gate Charge

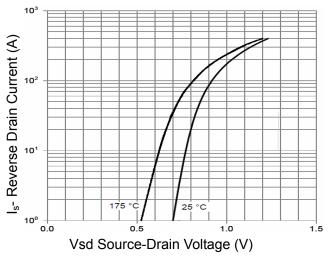


Figure 6 Source- Drain Diode Forward



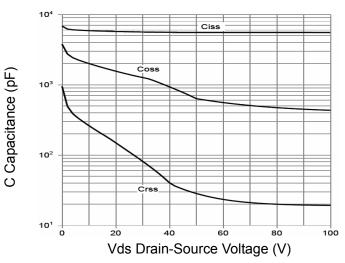


Figure 7 Capacitance vs Vds

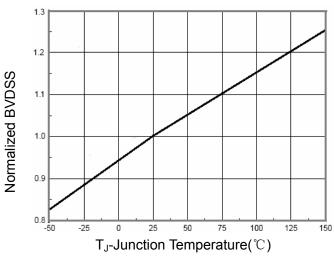


Figure 9 BV_{DSS} vs Junction Temperature

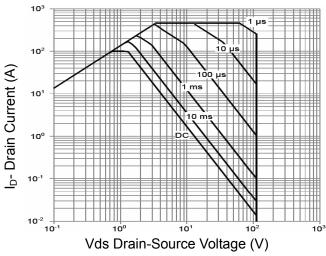


Figure 8 Safe Operation Area

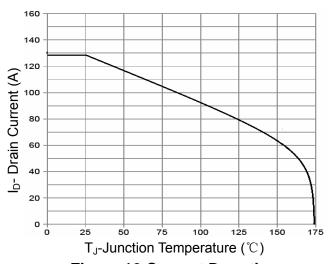


Figure 10 Current De-rating

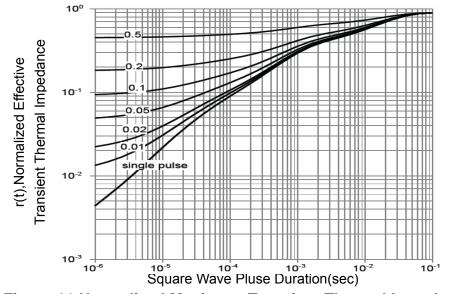
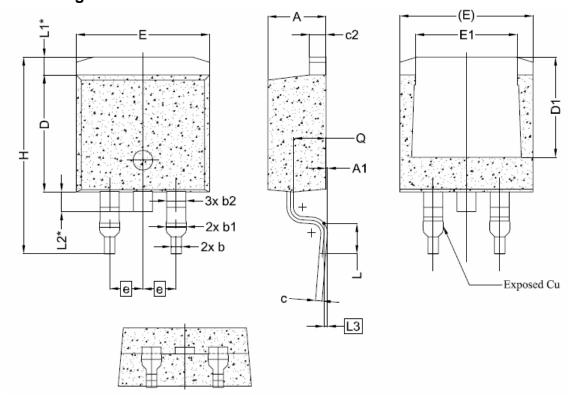


Figure 11 Normalized Maximum Transient Thermal Impedance



TO-263-2L Package Information



Symbol	Dimensions In Millimeters			
Symbol	Min.	Nom.	Max.	
A	4.24	4.44	4.64	
A1	0.00	0.10	0.25	
b	0.70	0.80	0.90	
b1	1.20	1.55	1.75	
b2	1.20	1.45	1.70	
С	0.40	0.50	0.60	
c2	1.15		1.40	
D	8.82	8.92	9.02	
D1	6.86	7.65	-	
E	9.96	10.16	10.36	
E1	6.89	7.77	7.89	
е	2.54BSC			
Н	14.61	15.00	15.88	
L	1.78	1.78 2.32		
L1	1.36 REF.			
L2	1.50 REF.			
L3	0.25 BSC			
Q	2.30	2.48	2.70	



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